

N-Channel 100 V (D-S) MOSFET

PRODUCT SUMMARY						
V _{DS} (V)	$R_{DS(on)}\left(\Omega\right)$	I _D (A) ^d	Q _g (Typ.)			
100	0.124 at V _{GS} = 10 V	4.2	4.6 nC			
100	0.128 at V _{GS} = 4.5 V	3.9	4.6110			

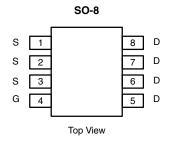
FEATURES

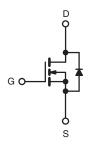
- TrenchFET® Power MOSFET
- 100 % UIS Tested

Pb-free ROHS COMPLIANT HALOGEN FREE

APPLICATIONS

- High Frequency Boost Converter
- LED Backlight for LCD TV





N-Channel MOSFET

ABSOLUTE MAXIMUM RATIN	IGS (T _A = 25 °C	, unless oth	erwise noted)	
Parameter	Symbol	Limit	Unit	
Drain-Source Voltage	V_{DS}	100	V	
Gate-Source Voltage	V_{GS}	± 20	v	
Continuous Drain Current (T _J = 150 °C)	$T_{C} = 25 ^{\circ}\text{C}$ $T_{C} = 70 ^{\circ}\text{C}$ $T_{A} = 25 ^{\circ}\text{C}$ $T_{A} = 70 ^{\circ}\text{C}$	I _D	4.2 3.5 3.0 ^{a, b}	A
Pulsed Drain Current $T_{C} = 25 ^{\circ}C$		I _{DM}	2.4 ^{a, b} 16	
Continuous Source-Drain Diode Current	T _A = 25 °C	- I _S	4.0 2 ^{a, b}	
Single Avalanche Current L = 0.1 mH		I _{AS}	6	Α
Single Avalanche Energy		E _{AS}	1.8	mJ
Maximum Power Dissipation	$T_{C} = 25 ^{\circ}\text{C}$ $T_{C} = 70 ^{\circ}\text{C}$ $T_{A} = 25 ^{\circ}\text{C}$ $T_{A} = 70 ^{\circ}\text{C}$	P _D	4.8 3 2.4 ^{a, b} 1.5 ^{a, b}	w
Operating Junction and Storage Temperatur	T _J , T _{stg}	- 55 to 150	°C	

THERMAL RESISTANCE RATINGS							
Parameter	Symbol	Typical	Maximum	Unit			
Maximum Junction-to-Ambient ^{a, c}	t ≤ 10 s	R_{thJA}	42	53	°C/W		
Maximum Junction-to-Foot (Drain)	Steady State	R_{thJF}	21	26	O/ V V		

Notes:

- a. Surface mounted on 1" x 1" FR4 board.
- b. t = 10 s.
- c. Maximum under steady state conditions is 85 $^{\circ}\text{C/W}.$
- d. Based on T_C = 25 °C.



Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static			L		L	1	
Drain-Source Breakdown Voltage	V _{DS}	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$	100			V	
V _{DS} Temperature Coefficient	ΔV _{DS} /T _J	J 050 A		110		mV/°C	
V _{GS(th)} Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	I _D = 250 μA		- 7.5			
Gate-Source Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}$, $I_{D} = 250 \mu A$	1		3	V	
Gate-Source Leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			± 100	nA	
	I _{DSS}	V _{DS} = 100 V, V _{GS} = 0 V			1	_	
Zero Gate Voltage Drain Current		V _{DS} = 100 V, V _{GS} = 0 V, T _J = 55 °C			10	- μΑ	
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \ge 5 \text{ V}, V_{GS} = 10 \text{ V}$	8			Α	
	5	$V_{GS} = 10 \text{ V}, I_D = 2.7 \text{ A}$	0.124			+	
Drain-Source On-State Resistance ^a	R _{DS(on)}	$V_{GS} = 4.5 \text{ V}, I_D = 2.5 \text{ A}$		0.128		Ω	
Forward Transconductance ^a	9 _{fs}	$V_{DS} = 10 \text{ V}, I_D = 2.7 \text{ A}$		7		S	
Dynamic ^b			L	<u> </u>		1	
Input Capacitance	C _{iss}			470			
Output Capacitance	C _{oss}	$V_{DS} = 50 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$		50		pF	
Reverse Transfer Capacitance	C _{rss}			25			
Total Cata Chargo	0	$V_{DS} = 50 \text{ V}, V_{GS} = 10 \text{ V}, I_{D} = 2.7 \text{ A}$		7.1	11	nC	
Total Gate Charge	Qg			4.6	7		
Gate-Source Charge	Q_{gs}	$V_{DS} = 50 \text{ V}, V_{GS} = 6 \text{ V}, I_{D} = 2.7 \text{ A}$		1.7			
Gate-Drain Charge	Q_{gd}			2			
Gate Resistance	R_g	f = 1 MHz		3		Ω	
Turn-On Delay Time	t _{d(on)}			10	15		
Rise Time	t _r	V_{DD} = 50 V, R_L = 23.8 Ω		10	15		
Turn-Off Delay Time	t _{d(off)}	$I_D\cong$ 2.1 A, V_{GEN} = 6 V, R_g = 1 Ω		10	15		
Fall Time	t _f			10	15		
Turn-On Delay Time	t _{d(on)}			10	15	ns	
Rise Time	t _r	V_{DD} = 50 V, R_L = 23.8 Ω		10	15		
Turn-Off Delay Time	t _{d(off)}	$I_D\cong$ 2.1 A, V_{GEN} = 10 V, R_g = 1 Ω		12	20		
Fall Time	t _f			10	15		
Drain-Source Body Diode Characteristi	cs		I.		l		
Continuous Source-Drain Diode Current	I _S	T _C = 25 °C			4	_	
Pulse Diode Forward Current	I _{SM}				8	_ ^	
Body Diode Voltage	V_{SD}	$I_S = 2.1 \text{ A}, V_{GS} = 0 \text{ V}$		0.8	1.2	٧	
Body Diode Reverse Recovery Time	t _{rr}			50	80	ns	
Body Diode Reverse Recovery Charge	Q _{rr}	L = 0.1 A dl/dt = 100 A/··· T		75	120	nC	
Reverse Recovery Fall Time	t _a	$I_F = 2.1 \text{ A}, \text{ dI/dt} = 100 \text{ A/}\mu\text{s}, T_J = 25 ^{\circ}\text{C}$		28			
Reverse Recovery Rise Time t _b				22		ns	

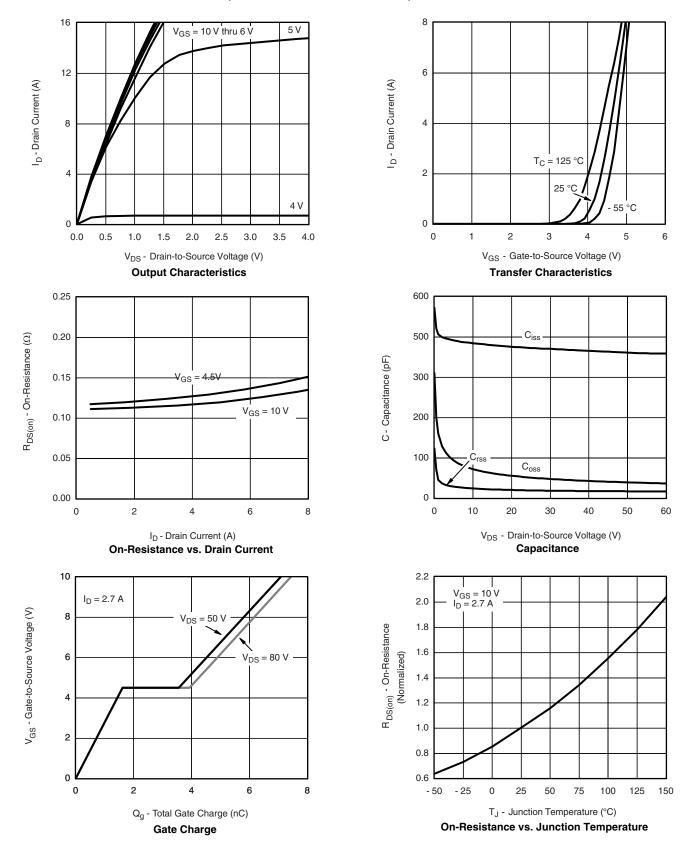
Notes:

2

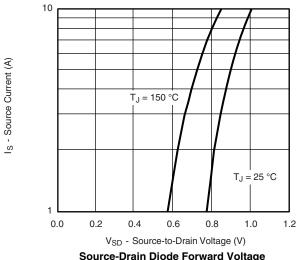
- a. Pulse test; pulse width \leq 300 $\mu s,$ duty cycle \leq 2 %
- b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

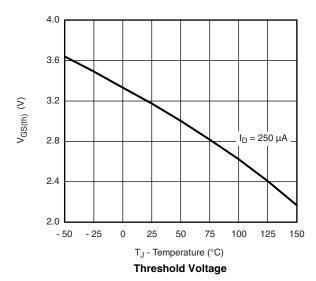


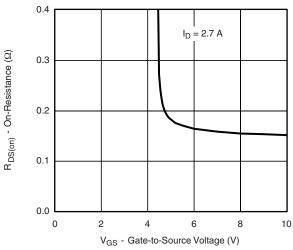




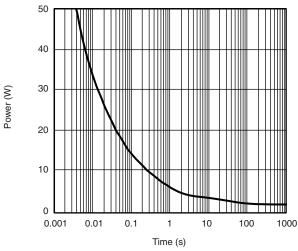


Source-Drain Diode Forward Voltage

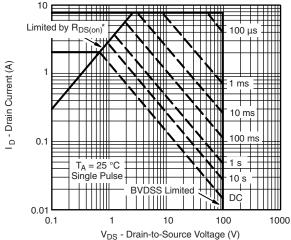




On-Resistance vs. Gate-to-Source Voltage



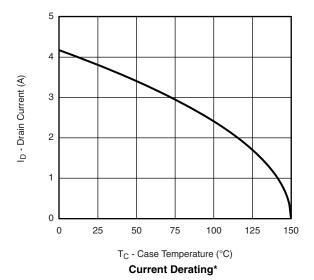
Single Pulse Power

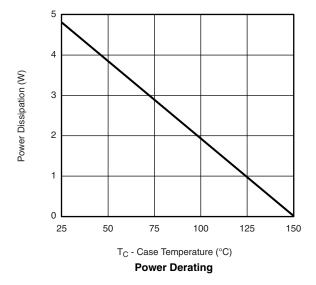


* $V_{GS} > \mbox{minimum} \ V_{GS}$ at which $R_{DS(on)}$ is specified

Safe Operating Area, Junction-to-Ambient

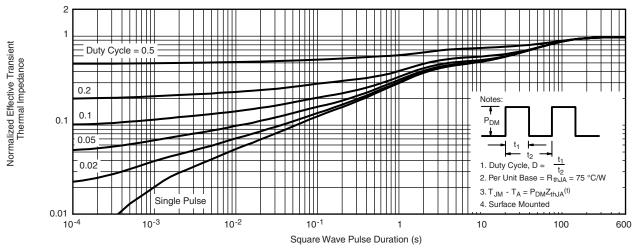




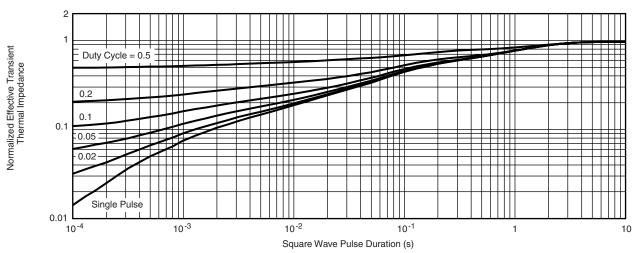


^{*} The power dissipation P_D is based on $T_{J(max.)} = 150$ °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.





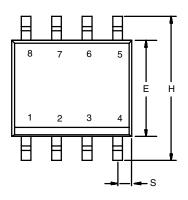
Normalized Thermal Transient Impedance, Junction-to-Ambient

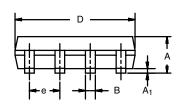


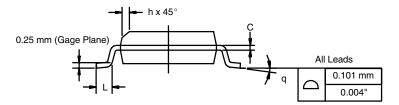
Normalized Thermal Transient Impedance, Junction-to-Foot



SOIC (NARROW): 8-LEADJEDEC Part Number: MS-012





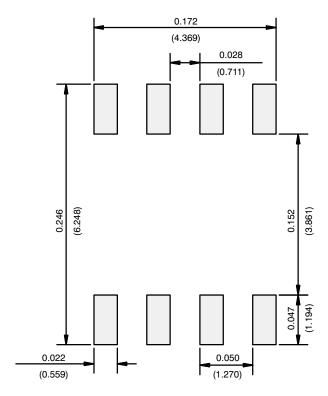


	MILLIM	IETERS	INC	INCHES		
DIM	Min	Max	Min	Max		
Α	1.35	1.75	0.053	0.069		
A ₁	0.10	0.20	0.004	0.008		
В	0.35	0.51	0.014	0.020		
С	0.19	0.25	0.0075	0.010		
D	4.80	5.00	0.189	0.196		
E	3.80	4.00	0.150	0.157		
е	1.27	BSC	0.050	0.050 BSC		
Н	5.80	6.20	0.228	0.244		
h	0.25	0.50	0.010	0.020		
L	0.50	0.93	0.020	0.037		
q	0°	8°	0°	8°		
S	0.44	0.64	0.018	0.026		
ECN: C-06527-Rev. I. 11-Sep-06						

DWG: 5498



RECOMMENDED MINIMUM PADS FOR SO-8



Recommended Minimum Pads Dimensions in Inches/(mm)



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